## Compact Slot / SMD Type (Slot width: 5 mm)

- Unique 5 mm Slot width.
- PCB surface mounting type.
- High resolution with a 0.5-mm-wide aperture.
- Choice of 2 types of Photo-IC output (EE-SX3350: Dark ON, EE-SX4350: Light ON).



## Ordering Information

Photomicrosensor

| Appearance | Sensing <br> method | Connecting <br> method | Sensing distance | Aperture size (H $\times$ W) <br> $(\mathbf{m m})$ | Output type | Model |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  |  |  |

Ratings, Characteristics and Exterior Specifications

Absolute Maximum Ratings ( $\mathrm{Ta}=25^{\circ} \mathrm{C}$ )

| Item | Symbol | Rated value | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: |
| Emitter |  |  |  |  |
| Forward current | IF | 30 | mA | --- *1 |
| Reverse voltage | $\mathrm{V}_{\mathrm{R}}$ | 4 | V | --- |
| Detector |  |  |  |  |
| Power supply voltage | Vcc | 16 | V | --- |
| Output voltage | Vout | 28 | V | --- |
| Output current | lout | 16 | mA | --- |
| Permissible output dissipation | Pout | 80 | mW | --- *1 |
| Operating temperature | Topr | -30 to +85 | ${ }^{\circ} \mathrm{C}$ | --- *1 |
| Storage temperature | $\mathrm{T}_{\text {stg }}$ | -40 to +100 | ${ }^{\circ} \mathrm{C}$ | --- *1 |
| Reflow soldering temperature | $\mathrm{T}_{\text {sol }}$ | 255 | ${ }^{\circ} \mathrm{C}$ | 10 sec . max. *2 |

*1. Continuous Forward Current and Collector Power Dissipation must be derated complying. The product should be used without freezing or condensation
*2. In case of reflow soldering, conditions which are shown at the temperature profile should be kept.

## Exterior Specifications

| Connecting method | Weight (g) | Material |
| :--- | :---: | :---: |
|  |  | Case |
| SMT | 0.3 | PPS |

Electrical and Optical Characteristics $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Item | Symbol | Value |  |  |  | Unit | Condition |  |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN. |  |  |  |  |  | TYP. | MAX. |

*1. Hysteresis denotes the difference in forward LED current value, expressed in percentage, calculated from the respective forward LED currents when the photo IC in turned from ON to OFF and when the photo IC in turned from OFF to ON.
*2. The value of the response frequency is measured by rotating the disk as shown below.


*3. The following illustrations show the definition of response delay time. The value in the parentheses applies to the EE-SX4350.


EE-SX3350


EE-SX4350

## Engineering Data (Reference value)

Fig 1. Forward Current vs. Collector Dissipation Temperature Rating


Fig 4.LED Current vs. Ambient Temperature Characteristics (Typical)


Fig 7. Current Consumption vs. Supply Voltage (Typical)


Fig 2. Forward Current vs. Forward Voltage Characteristics (Typical)


Fig 5. Low-level Output Voltage vs. Output Current (Typical)


Fig 8. Response Delay Time vs. Forward Current (Typical)


Fig 3. LED Current vs. Supply Voltage (Typical)


Fig 6. Low-level Output Voltage vs. Ambient Temperature Characteristics (Typical)


Fig 9. Repeat Sensing Position Characteristics (Typical)


## Safety Precautions

To ensure safe operation, be sure to read and follow the Instruction Manual provided with the Sensor.

| CAUTION |
| :--- |
| This product is not designed or rated for ensuring |
| safety of persons either directly or indirectly. Do not |
| use it for such purposes. |

## Precautions for Safe Use

Do not use the product with a voltage or current that exceeds the rated range.
Applying a voltage or current that is higher than the rated range may result in explosion or fire.
Do not miswire such as the polarity of the power supply voltage.
Otherwise the product may be damaged or it may burn
Do not short-circuit the load.
Otherwise explosion or burning may occur.
This product does not resist water. Do not use the product in places where water or oil may be sprayed onto the product.

## Precautions for Correct Use

Do not use the product in atmospheres or environments that exceed product ratings. This product is for surface mounting. Refer to Soldering Information, Storage and Baking for details.
Dispose of this product as industrial waste.

Dimensions and Internal Circuit
Photomicrosensor
EE-SX3350
EE-SX4350


Aperture size $(\mathrm{H} \times \mathrm{W})$

| Emitter | Detector |
| :---: | :---: |
| $1.4 \times 1.4$ | $1.4 \times 0.5$ |



## Tape and Reel

## Reel (Unit: mm)*



Tape (Unit: mm)


Note: Direction of product packing is upper figure.

## Tape quantity

400 pcs./reel
50 pcs./pack *

* EE-SX3350-1/EE-SX4350-1 (50 pcs./pack) has no reel, only tape is attached.


## Soldering Information

## Reflow soldering : Temperature profile

1. The reflow soldering can be implemented in two times complying with the following diagram.
All the temperatures in the product must be within the diagram.
2. The recommended thickness of the metal mask for screen printing is between 0.2 and 0.25 mm .


## Storage

## Storage conditions

To protect the product from the effects of humidity until the package is opened, dry-box storage is recommended. If this is not possible, store the product under the following conditions:

Temperature: 10 to $30^{\circ} \mathrm{C}$
Humidity: $60 \%$ RH max.

## Manual soldering

The manual soldering should not be applied to the products, otherwise the housing may be deformed and/or the Au plating may be peeled off by heat.

## Other notes

The use of infrared lamp causes the temperature at the resin to rise particularly too high.
All the temperatures in the product must be within the above diagram. Do not immerse the resin part into the solder. Even if within the above temperature diagram, there is a possibility that the gold wire in the products is broken in case that the deformation of PC board gives stress to the products.
Please confirm the conditions (including material and method of flux and cleaning) of the reflow soldering fully by actual solder reflow machine prior to the mass production use.

## Baking

In case that it could not carry out the above treatment, it is able to mount by the following baking treatment. However baking treatment shall be limited only 1 time.

Recommended conditions: $60^{\circ} \mathrm{C}$ for 24 to 48 hours (reeled one)
$100^{\circ} \mathrm{C}$ for 8 to 24 hours (loose one)

## Treatment after open

1. Reflow soldering must be done within 48 hours stored at the conditions of humidity $60 \%$ RH or less and temperature 10 to $30^{\circ} \mathrm{C}$.
2. If the product must be stored after it is unpacked, store it in a dry box or reseal it in a moisture-proof package with desiccant at a temperature of 10 to $30^{\circ} \mathrm{C}$ and a humidity of $60 \%$ RH or less. Even then, mount the product within one week.

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